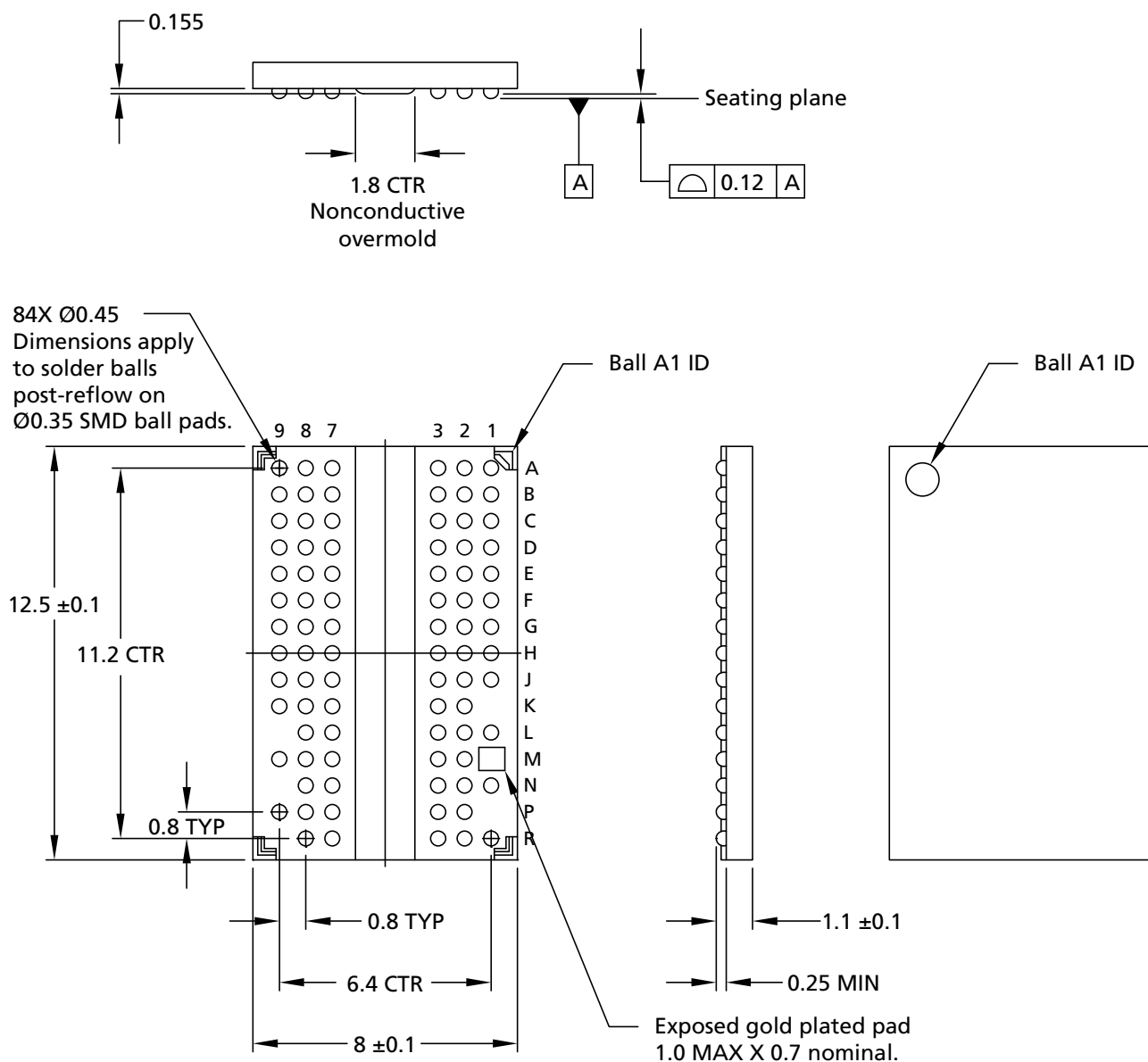


## Packaging

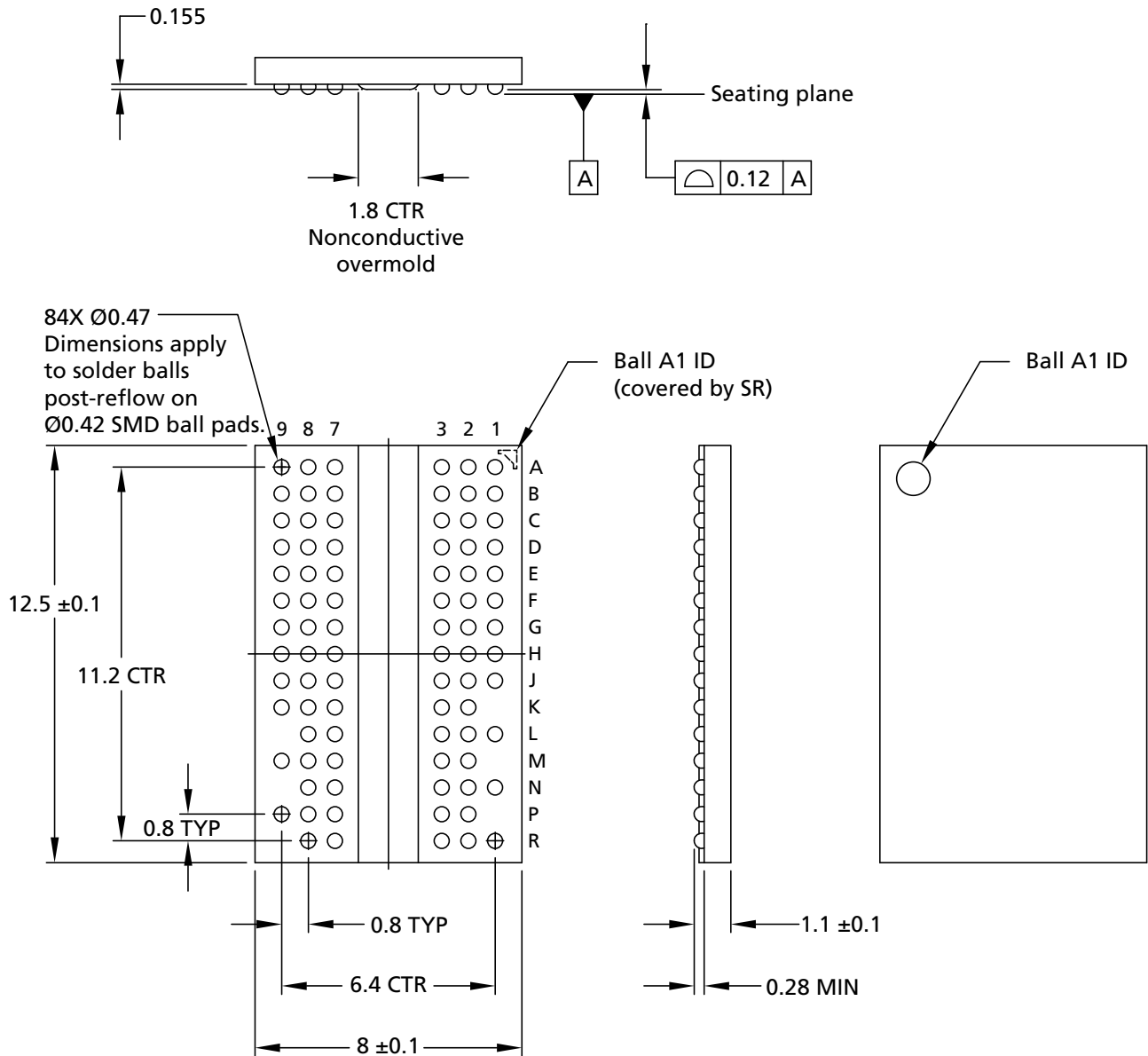
### Package Dimensions

**Figure 8: 84-Ball FBGA Package (8mm x 12.5mm) – x16 Die Rev :H**



- Notes:
1. All dimensions are in millimeters.
  2. Solder ball material: SAC305 (96.5% Sn, 3% Ag, 0.5% Cu) or leaded Eutectic (62% Sn, 36%Pb, 2% Ag).

**Figure 10: 84-Ball FBGA Package (8mm x 12.5mm) – x16; "NF" Die Rev :M**



- Notes:
1. All dimensions are in millimeters.
  2. Solder ball material: SAC305 (96.5% Sn, 3% Ag, 0.5% Cu).